鴻勁精密股份有限公司
HON.PRECISION, INC.

股票代號7769

2026Q2
法人說明會簡報

(2026/07)

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AGENDA

01

財務表現

Profitability

02

營運概況及未來展望

Operation Update and Outlook

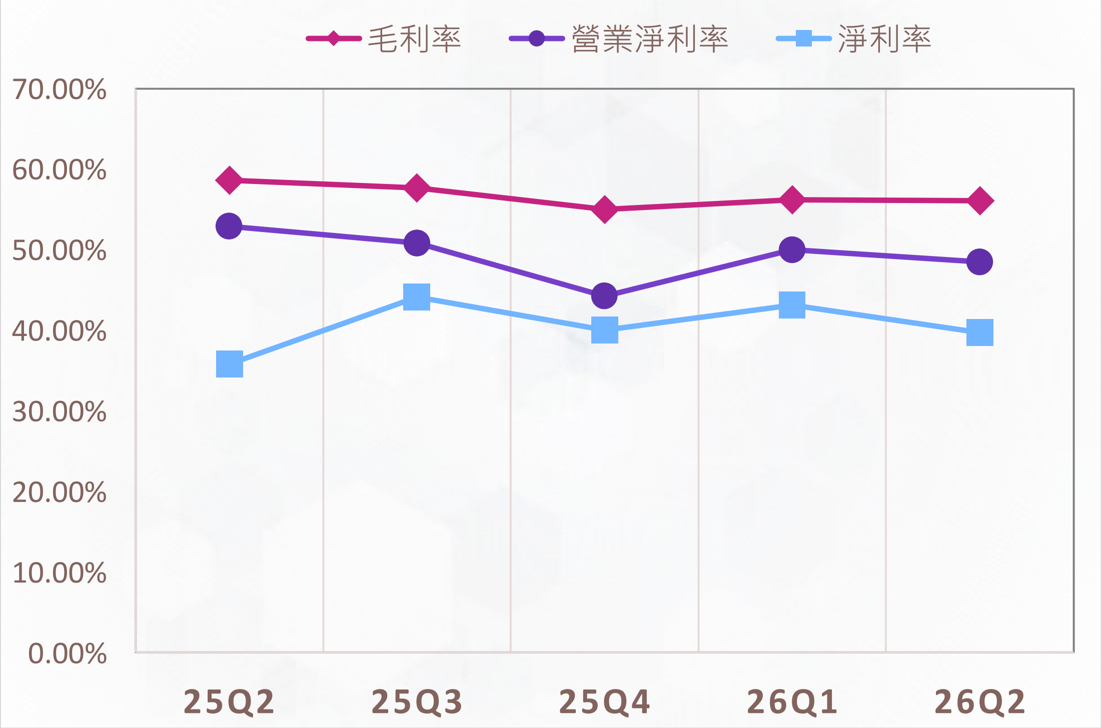
財務表現

Profitability

- 財務報表
- 獲利趨勢

獲利趨勢

	營業收入 (仟元)	毛利率	EPS (元)
2026 H1	24,518,966	56.15%	56.14
2025	30,270,625	56.54%	75.71
2024	13,992,344	55.02%	32.95



財務報表

TWD ：仟元

	25H1	%	25H2	%	2025	%	26H1	%
營業收入	12,797,230	100.0	17,473,395	100.0	30,270,625	100.0	24,518,966	100.0
營業毛利	7,530,955	58.8	9,582,681	54.8	17,113,636	56.5	13,768,304	56.2
營業費用	754,441	5.9	1,313,492	7.5	2,067,933	6.8	1,722,048	7.0
營業淨利	6,776,514	53.0	8,269,189	47.3	15,045,703	49.7	12,046,256	49.1
年度淨利	5,033,752	39.3	7,328,044	41.9	12,361,796	40.8	10,100,517	40.7

營運概況
及未來展望

Operation Update and Outlook

- 訂單應用別分布
- 營運概況及未來展望

2026Q2 法人說明會簡報

訂單應用別分布

2026 H1

77%

▲ from 72% (2025)

- AI Computing
- Server
- Networking
- APU/GPU/CPU/FPGA

2026 H1

9%

▼ from 11% (2025)

- Sensor
- MCU
- LiDAR

2026 H1

8%

▼ from 10% (2025)

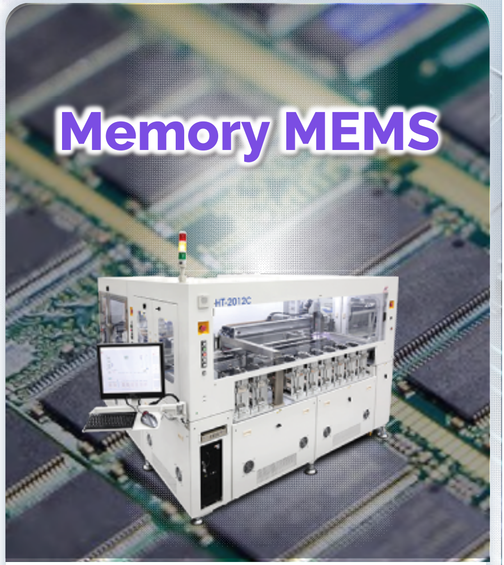
- SiP
- 5G OTA
- Power, PMIC
- Mobile Phone/AP
- RF Related Devices

2026 H1

5%

▶ from 5% (2025)

- AR glasses
- LCD driver
- CIS



2026 H1

1%

▼ from 2% (2025)

- Flash/DRAM Memory
- Accelerometer
- Gyroscope
- Barometer
- Light Sensor
- Pressure Sensor

營運概況及未來展望-1

01 Capacity

- 26H1實際成長率 45%+
  - 接單能見度至26年底，產能規劃至27Q1
- 27年產能擴充計畫：+50%
  - 德勝廠27Q1投產，預計提升15%產能
  - 中國在地生產 27Q1，預計提升20%產能
  - 現有總部廠區，預計提升15%產能

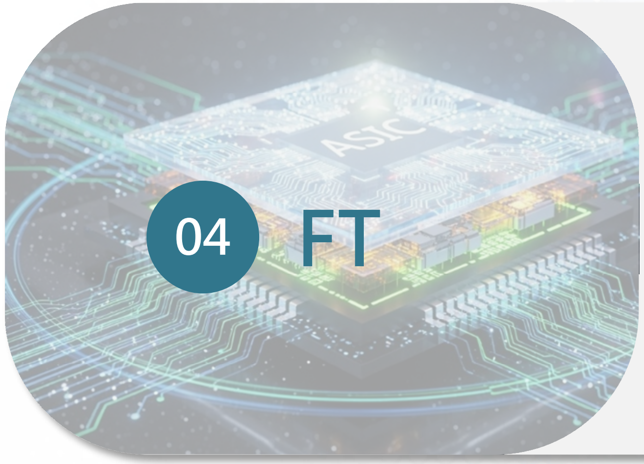
02 客戶擴廠需求

- 26H2~27：美系車用晶片客戶泰國廠
- 27Q1：OSAT美國/新加坡新廠，以及中國新廠
- 27Q2：OSAT亞利桑那州新廠

03 CPO/CPC

- INS4 OE，更新進度(完成SOW)，預計26年10月開始出貨
- CPO lab (clean room) 已建置完成，支援各家客戶工程驗證需求
- 與主要 ATE 大廠持續開發INS3、INS4，多個專案進行中
- 與美系網通大客戶及ATE大廠 共同開發CPC專案

營運概況及未來展望-2



- 美系EV大廠AI晶片採最高階機台，26H2 持續出貨，出貨至美國，以及台灣&韓國OSAT
- 中國市場高階AI/HPC 需求強勁，訂單數量年增60%+
- TPU大廠 26H2 大量出機，交付至台灣/新加坡OSAT
- 美系車用晶片客戶 26H2 大量出機，交貨至泰國新廠
- 美系Austin客戶下一世代CPU 驗證完成，27年需求強勁
- 大package + automation + advanced ATC(~10kW)， 26年10月開始出貨

- 中國市場車用與AI測試需求強勁，訂單數量年增80%
- 美系Austin客戶CPU 26H2開始出貨，GPU產品驗證中
- 美系EV大廠量產導入三溫SLT
- 美系GPU大客戶工程驗證機完成第一階段驗證，持續優化中
- 美系CSP客戶下世代CPU+TPU導入中，驗證機台預計26年9月至12月陸續出貨
- 中國市場MSLT(multi-site SLT)業務推展

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Efficient Tomorrow.

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Questions & Answers